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(57) **ABSTRACT**

A method for producing a wiring circuit board includes a first step of preparing a wiring circuit board assembly sheet including a support sheet, a plurality of wiring circuit boards supported by the support sheet, and a joint connecting the support sheet to the plurality of wiring circuit boards, having flat-shaped one surface and the other surface facing one surface at spaced intervals thereto in a thickness direction, and having a thin portion in which the other surface is recessed toward one surface and a second step of forming a burr portion protruding toward the other side in the thickness direction and cutting the thin portion.

